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ELECTRONIC COMPONENT PACKAGE AND MOUNTING THEREOF

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Abstract

PURPOSE: To provide electronic component packages, which respectively make a wiring of a power-supply electrode or a GND electrode on a printed board facilitate and decrease the time for an automatic mounting process.

CONSTITUTION: Electronic component package main bodies 1 respectively have the same electrodes 2 for surface mounting use and for general signal use as conventional ones and either of power-supply and GND electrodes 5 and 6 for printed board insertion use, a general signal conductor is connected to pads 2 on a printed board and the electrodes 5 and 6 are respectively inserted in holes for component insertion use in the printed board 7 and are mounted in a state that they are respectively connected to a power-supply layer 9 and a GND layer 8.

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